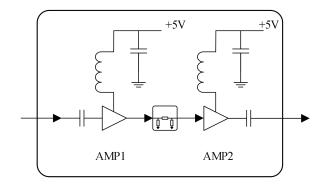


Low noise amplifier chip, 1~9GHz

Performance characteristics

- Operating frequency: 1~9GHz
- Gain: 31dB
- NF: 1.5dB
- P-1dB: 15dBm
- Quiescent current: 90mA
- Outline Dimensions: 10x8x2.5mm

Principle diagram



Product introduction

GF020109Q1 low noise amplifier chip adopts GaAs technology, with a frequency range of 1-9GHz, a small signal gain of 31dB, an in band noise figure of 1.5dB, a +5V power supply, and it is housed in a ceramic package, suitable for SMT.

Absolute maximum ratings			
Parameter	Ratings		
VDD	+7V		
Input power	+20dBm		
Operating temperature	-55∼+85° C		
Storage temperature	-55~+150°C		
Note: Exceeding any of these limits may cause permanent damage.			

Low noise amplifier chip, 1~9GHz

Electrical parameters(TA = +25°C, 50 Ω system)					
Parameter	Min	Тур	Max	Unit	
Operating frequency	1		9	GHz	
gain		31		dB	
Gain flatness		±0.8		dB	
Noise coefficient		1.5		dB	
input return loss		-12		bit	
Output Return Loss		-12		dB	
P-1dB		15		dB	
Quiescent current		90		dB	

Main indicator testing curve

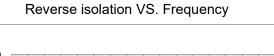
Gain VS. Frequency Noise figure VS. Frequency 10 45 43 9 41 8 Noise Figure (dB) 7 39 37 6 35 5 \$21@25°C 33 4 Gain NF@25°C 31 3 29 2 27 1 25 0 1.0 1.8 2.6 3.4 4.2 5.0 5.8 6.6 7.4 8.2 9.0 7.0 9.0 1.0 2.0 3.0 4.0 5.0 6.0 8.0 Frequency (GHz) Frequency (GHz) Input return loss VS. Frequency Output return loss VS. Frequency 0 0 -5 -5 Output Return Loss (dB) Input Return Loss (dB) -10 -10 -15 -15 -20 -20 -25 -25 S11@25°C S22@25°C -30 -30 -35 -35 -40 -40 1.0 1.8 9.0 2.6 3.4 4.2 5.0 5.8 6.6 7.4 8.2 1.0 1.8 2.6 5.0 5.8 8.2 9.0 3.4 4.2 6.6 7.4 Frequency (GHz)

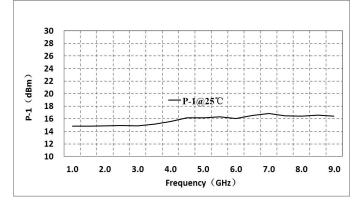
Frequency (GHz)

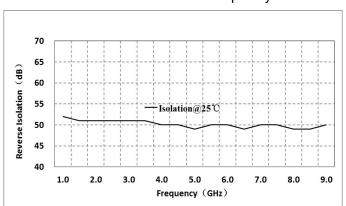


Low noise amplifier chip, 1~9GHz

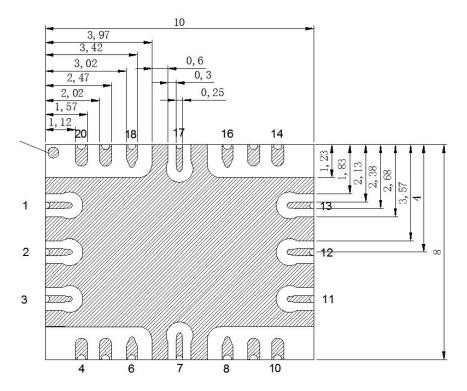
P-1 VS. Frequency







External structure



Pin	Function	Description	
1、13	+5V	+5V power supply	
2	RFin	RF input, no need for blocking capacitors	
3~11	GND	Ground	
12	RFout	RF output, no need for blocking capacitors	
14~20	GND	Ground	



Low noise amplifier chip, $1 \sim 9$ GHz

Note:

- Unit: mm;
- The device should be stored in a dry and nitrogen environment. When the device cannot be used up after being unpacked, it should be immediately stored in a drying oven or vacuum sealed to avoid absorbing moisture from the air;
- Devices are sensitive to static electricity, and attention should be paid to anti-static measures during storage, transportation, assembly, and use;
- Please connect all grounding pins to RF ground;
- This product is suitable for reflow soldering installation process, with a maximum reflow soldering peak temperature of 260 °C.